PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Arito OGAWA	07/06/2010
Sadayoshi HORII	07/06/2010
Taketoshi SATO	07/06/2010
Hideharu ITATANI	07/06/2010
Nobuyuki MISE	07/20/2010
Osamu TONOMURA	07/23/2010

RECEIVING PARTY DATA

Name:	Hitachi Kokusai Electric, Inc.	
Street Address:	14-1 Sotokanda 4-chome, chiyoda-ku,	
City:	Tokyo	
State/Country:	JAPAN	
Postal Code:	1018980	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12825012

CORRESPONDENCE DATA

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NAME OF SUBMITTER: Carl I. Brundidge

PATENT

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OF \$40.00 12825012

Total Attachments: 2

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PATENT REEL: 024834 FRAME: 0299

ASSIGNMENT

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to the undersigned by Hitachi Kokusai Electric, Inc., a corporation organized under the laws of Japan, located at 14-1 Sotokanda 4-chome, Chiyoda-ku, Tokyo 1018980, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi Kokusai Electric, Inc., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE AND SUBSTRATE PROCESSING SYSTEM

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi Kokusai Electric, Inc., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi Kokusai Electric, Inc.

Signed on the date(s) indicated aside signatures:

INVENTOR(S)	Date Signed
1) Arito Ogawa	
Avito Ogama	July 6. 2010
2) Sadayoshi Horii	
Sadayoshi Hori	July 6. 2010
3) Taketoshi Sato	/
Taketohi Sato	July 6,2010

PATENT REEL: 024834 FRAME: 0300

41	Hideharu	T4-4
4)	muenaru	matani

Kideharu Hatani

July 6, 2010

5) Nobuyuki Mise

Nobuyaki Mise

July 20, 2010

6) Osamu Tonomura

Osamu Tonomura

July 23. 20/0

RECORDED: 08/13/2010 REEL: 024834 FRAME: 0301